



Material Content Data Sheet



Sales Product Name	TLF1963TE			Issued	25. September 2017			
MA#	MA001040850							
Package	PG-TO252-5-11			Weight*	365.15 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.428	1.21	1.21	12128	12128
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		168	
	non noble metal	iron	7439-89-6	0.205	0.06		560	
	non noble metal	copper	7440-50-8	204.243	55.94	56.02	559346	560074
	non noble metal	aluminium	7429-90-5	0.195	0.05	0.05	535	535
wire	non noble metal	aluminium	7429-90-5	0.195	0.05	0.05	535	535
encapsulation	organic material	carbon black	1333-86-4	0.295	0.08		807	
	plastics	epoxy resin	-	13.548	3.71		37104	
	inorganic material	silicondioxide	60676-86-0	133.423	36.54	40.33	365397	403308
leadfinish	non noble metal	tin	7440-31-5	5.072	1.39	1.39	13892	13892
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	209	210
solder	non noble metal	tin	7440-31-5	0.072	0.02		197	
	noble metal	silver	7440-22-4	0.090	0.02		246	
	non noble metal	lead	7439-92-1	3.436	0.94	0.98	9410	9853
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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